# 4-Bit Full Adder

The MC14008B 4-bit full adder is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. This device consists of four full adders with fast internal look-ahead carry output. It is useful in binary addition and other arithmetic applications. The fast parallel carry output bit allows high-speed operation when used with other adders in a system.

- Look–Ahead Carry Output
- Diode Protection on All Inputs
- All Outputs Buffered
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low–power TTL Loads or One Low–power Schottky TTL Load Over the Rated Temperature Range
- Pin-for-Pin Replacement for CD4008B



Symbol	Parameter	Value	Unit
$V_{DD}$	DC Supply Voltage Range	-0.5 to +18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage Range (DC or Transient)	-0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient) per Pin	±10	mA
P <sub>D</sub>	Power Dissipation, per Package (Note 3.)	500	mW
T <sub>A</sub>	Ambient Temperature Range	-55 to +125	°C
T <sub>stg</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

- Maximum Ratings are those values beyond which damage to the device may occur.
- Temperature Derating: Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.



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### MARKING DIAGRAMS

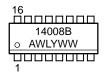


PDIP-16 P SUFFIX CASE 648



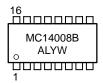


SOIC-16 D SUFFIX CASE 751B





SOEIAJ-16 F SUFFIX CASE 966



A = Assembly Location

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week

#### **ORDERING INFORMATION**

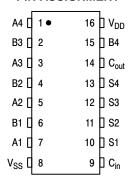
Device	Package	Shipping
MC14008BCP	PDIP-16	2000/Box
MC14008BDR2	SOIC-16	2500/Tape & Reel
MC14008BF	SOEIAJ-16	See Note 1.

 For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

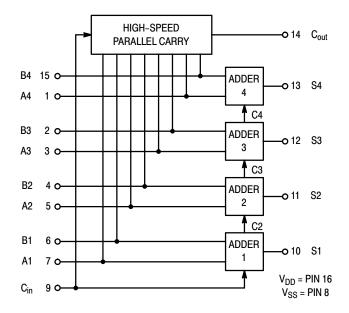
TRUTH TABLE (One Stage)

C <sub>in</sub>	В	Α	Cout	S
0	0	0	0	0
0	0	1	0	1
0	1	0	0	1
0	1	1	1	0
1	0	0	0	1
1	0	1	1	0
1	1	0	1	0
1	1	1	1	1

#### **PIN ASSIGNMENT**



#### **BLOCK DIAGRAM**



## **ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

			V <sub>DD</sub>	- 5	5°C		25°C		125	5°C	
Characteristic		Symbol	Vdc	Min	Max	Min	Typ <sup>(4.)</sup>	Max	Min	Max	Unit
Output Voltage V <sub>in</sub> = V <sub>DD</sub> or 0	"0" Level	V <sub>OL</sub>	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
V <sub>in</sub> = 0 or V <sub>DD</sub>	"1" Level	V <sub>OH</sub>	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Input Voltage $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	"0" Level	V <sub>IL</sub>	5.0 10 15		1.5 3.0 4.0		2.25 4.50 6.75	1.5 3.0 4.0		1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V <sub>IH</sub>	5.0 10 15	3.5 7.0 11	_ _ _	3.5 7.0 11	2.75 5.50 8.25	_ _ _	3.5 7.0 11	_ _ _	Vdc
Output Drive Current $(V_{OH} = 2.5 \text{ Vdc})$ $(V_{OH} = 4.6 \text{ Vdc})$ $(V_{OH} = 9.5 \text{ Vdc})$ $(V_{OH} = 13.5 \text{ Vdc})$	Source	I <sub>OH</sub>	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	_ _ _ _	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	_ _ _ _	- 1.7 - 0.36 - 0.9 - 2.4	_ _ _ _	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I <sub>OL</sub>	5.0 10 15	0.64 1.6 4.2	_ _ _	0.51 1.3 3.4	0.88 2.25 8.8	_ _ _	0.36 0.9 2.4	_ _ _	mAdc
Input Current		I <sub>in</sub>	15	_	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)		C <sub>in</sub>	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)		I <sub>DD</sub>	5.0 10 15	_ _ _	5.0 10 20	_ _ _	0.005 0.010 0.015	5.0 10 20	_ _ _	150 300 600	μAdc
Total Supply Current <sup>(5.)</sup> (6.) (Dynamic plus Quiescer Per Package) (C <sub>L</sub> = 50 pF on all output buffers switching)	nt,	I <sub>T</sub>	5.0 10 15			$I_T = (3)$	1.7 μΑ/kHz) f 3.4 μΑ/kHz) f 5.0 μΑ/kHz) f	+ I <sub>DD</sub>			μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

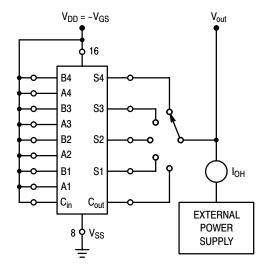
$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where:  $I_T$  is in  $\mu A$  (per package),  $C_L$  in pF,  $V = (V_{DD} - V_{SS})$  in volts, f in kHz is input frequency, and k = 0.005.

## SWITCHING CHARACTERISTICS (7.) ( $C_L = 50 \text{ pF}, T_A = 25^{\circ}\text{C}$ )

Characteristic	Symbol	V <sub>DD</sub> Vdc	Min	Тур <sup>(8.)</sup>	Max	Unit
Output Rise and Fall Time	t <sub>TLH</sub> ,					ns
$t_{TLH}$ , $t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$	t <sub>THL</sub>	5.0	_	100	200	
$t_{TLH}$ , $t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$		10	_	50	100	
$t_{TLH}$ , $t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$		15	_	40	80	
Propagation Delay Time	t <sub>PLH</sub> , t <sub>PHL</sub>					ns
Sum in to Sum Out						
$t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 315 \text{ ns}$		5.0	_	400	800	
$t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 127 \text{ ns}$		10	_	160	320	
$t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 90 \text{ ns}$		15	_	115	230	
Sum In to Carry Out						
$t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 220 \text{ ns}$		5.0	_	305	610	
$t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 112 \text{ ns}$		10	_	145	290	
$t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 85 \text{ ns}$		15	_	110	220	
Carry In to Sum Out						
$t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 290 \text{ ns}$		5.0	_	375	750	
$t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 122 \text{ ns}$		10	_	155	310	
$t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 90 \text{ ns}$		15	_	115	230	
Carry In to Carry Out						
$t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 85 \text{ ns}$		5.0	_	170	340	
$t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 42 \text{ ns}$		10	_	75	150	
$t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 30 \text{ ns}$		15		55	110	

- 7. The formulas given are for the typical characteristics only at 25°C.
  8. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



**Figure 1. Typical Source Current** Characteristics Test Circuit

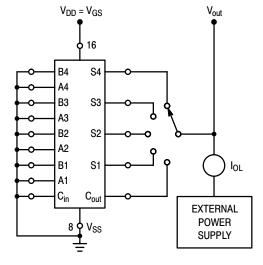


Figure 2. Typical Sink Current **Characteristics Test Circuit** 

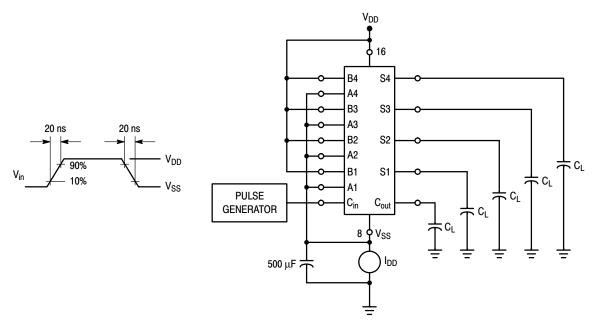


Figure 3. Dynamic Power Dissipation Test Circuit and Waveform

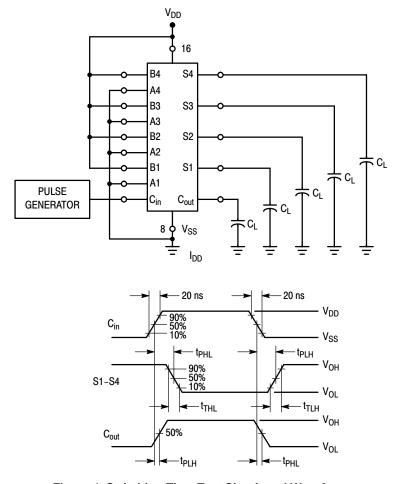


Figure 4. Switching Time Test Circuit and Waveforms

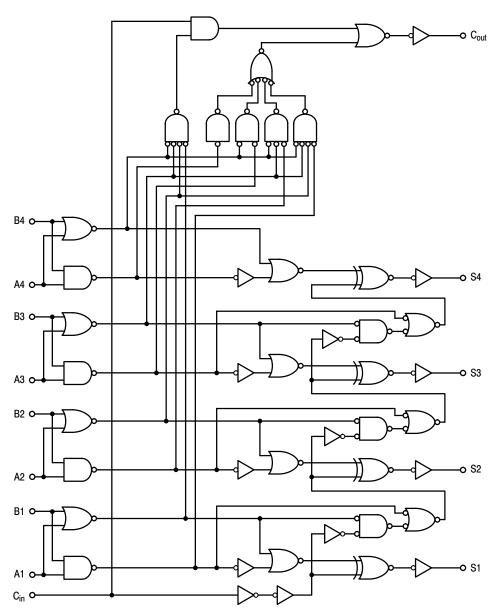
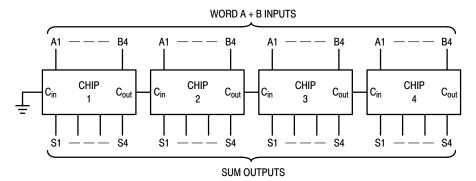


Figure 5. Logic Diagram

#### **TYPICAL APPLICATION**



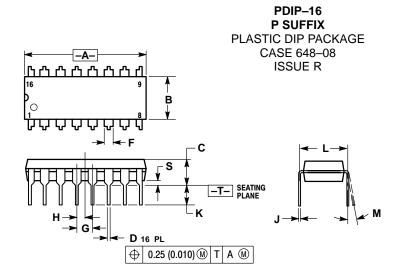
Calculation of 16-bit adder speed:

 $t_P$  total =  $t_P$  (Sum to Carry) +  $t_P$  (Carry to Sum) + 2  $t_P$  (Carry to Carry) The guaranteed 16-bit adder speed at 10 V, 25°C,  $C_L$  = 50 pF is:

 $t_p \text{ total} = 290 + 310 + 300 = 900 \text{ ns}$ 

Figure 6. Using the MC14008B in a 16-Bit Adder Configuration

#### **PACKAGE DIMENSIONS**



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: INCH.

  3. DIMENSION LTO CENTER OF LEADS WHEN FORMED PARALLEL.

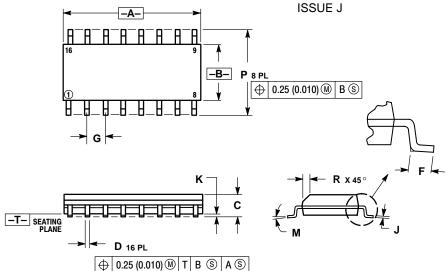
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

  5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54	BSC
Н	0.050	BSC	1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10 °
S	0.020	0.040	0.51	1.01

#### SOIC-16 **D SUFFIX**

PLASTIC SOIC PACKAGE CASE 751B-05



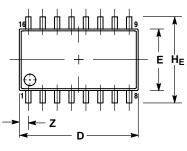
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI
- 1. DIMENSIONING AND TOLEHANCING PER ANY Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- MAXIMUM MOLD FRO HOSIGIA 4.15 (5.655)
  PER SIDE.
  DIMENSION D DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.127 (6.065) TOTAL
  IN EXCESS OF THE D DIMENSION AT
  MAXIMUM MATERIAL CONDITION.

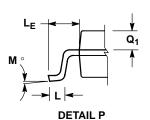
	MILLIN	IETERS	ERS INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	9.80	10.00	0.386	0.393		
В	3.80	4.00	0.150	0.157		
С	1.35	1.75	0.054	0.068		
D	0.35	0.49	0.014	0.019		
F	0.40	1.25	0.016	0.049		
G	1.27	BSC	0.050	50 BSC		
J	0.19	0.25	0.008	0.009		
K	0.10	0.25	0.004	0.009		
M	0°	7°	0°	7°		
P	5.80	6.20	0.229	0.244		
R	0.25	0.50	0.010	0.019		

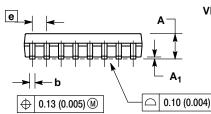
#### PACKAGE DIMENSIONS

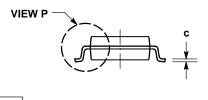
#### SOEIAJ-16 **F SUFFIX**

PLASTIC EIAJ SOIC PACKAGE CASE 966-01 **ISSUE O** 









#### NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982
- CONTROLLING DIMENSION: MILLIMETER. I. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15
- (0.006) PER SIDE.

  TERMINAL NUMBERS ARE SHOWN FOR
- 4. TEHMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) DAMBAR FRO INJSION STRALL BE USO (0.005)
  TOTAL IN EXCESS OF THE LEAD WIDTH
  DIMENSION AT MAXIMUM MATERIAL CONDITION.
  DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE
  BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050	BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10°
$Q_1$	0.70	0.90	0.028	0.035
Z		0.78		0.031

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